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Part Number: [0783210006](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR3 DIMM Socket, LLCR, Vertical, Through Hole, with Beveled Metal Pins, Black Housing, Natural (Off-White) Latches, 0.38µm (15µ") Gold (Au) Plating, 2.67mm (.105") Solder Tail Length, 1.57mm (.062") PCB Thickness, 240 Circuits, Lead free

Documents:
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-78321-002 \(PDF\)](#)

Agency Certification

CSA	LR19980
UL	E29179

General

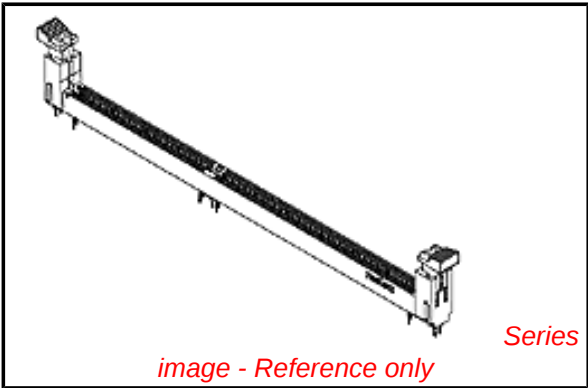
Product Family	Memory Module Sockets
Series	78321
Component Type	Socket
JEDEC Outline	MO-269
Product Name	DDR3 DIMM

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Color - Resin	Black, Natural
Durability (mating cycles max)	25
Entry Angle	Vertical
Flammability	94V-0
Function Key	None
Keying to Mating Part	Yes
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
PC Tail Length (in)	0.105 In
PC Tail Length (mm)	2.67 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.062 In
PCB Thickness Recommended (mm)	1.57 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Pitch - Term. Interface (in)	0.039 In
Pitch - Term. Interface (mm)	1.00 mm
Plating min: Mating (µin)	15
Plating min: Mating (µm)	0.38
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.54
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	1A
Voltage - Maximum	30V AC (RMS)/DC



EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Not Reviewed
Halogen-Free
Status
Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[78321Series](#)

Mates With
JEDEC standard 1.27mm modules

Voltage Key	Center
Solder Process Data	
Duration at Max. Process Temperature (seconds)	10
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	2
Process Temperature max. C	260

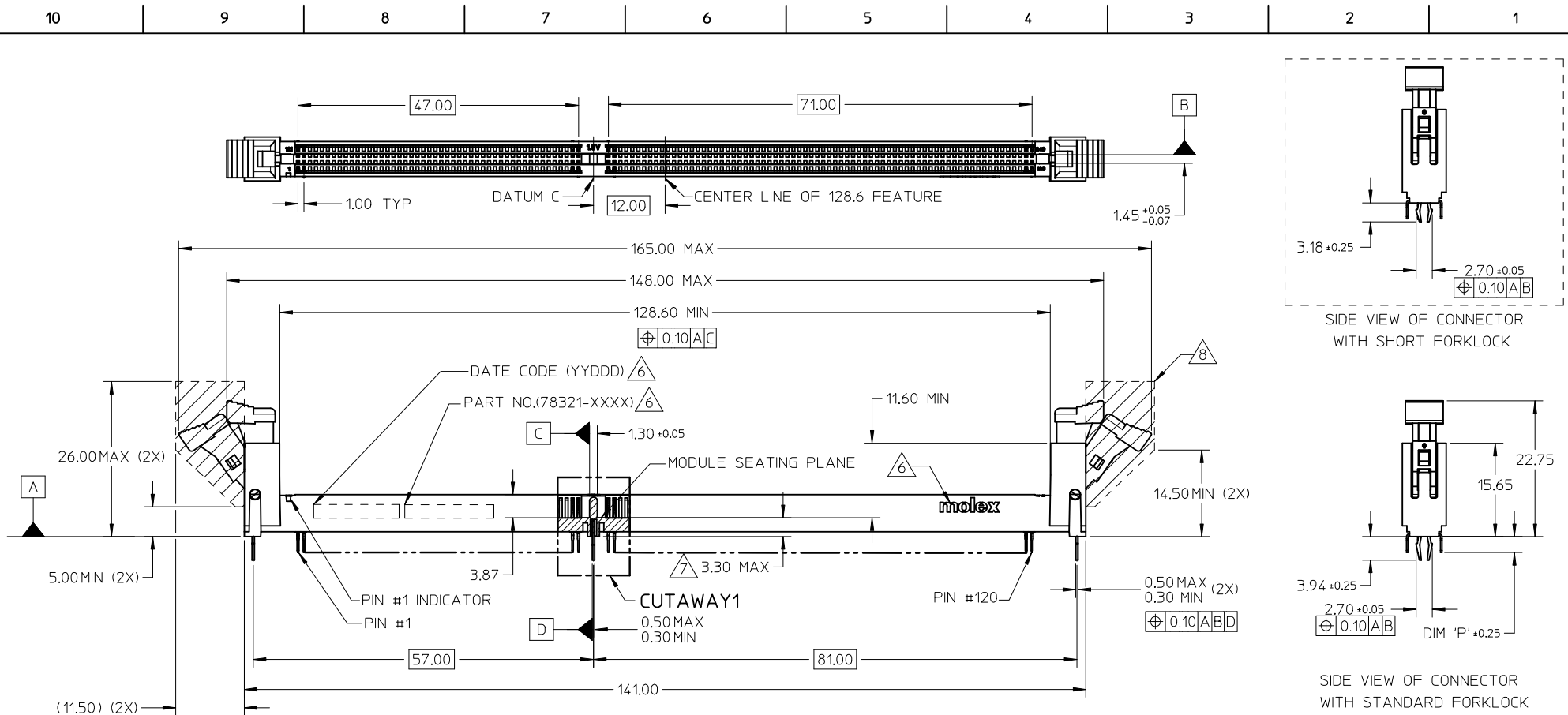
Material Info

Reference - Drawing Numbers

Packaging Specification	PK-78321-001
Product Specification	PS-78321-002
Sales Drawing	SD-78321-001

This document was generated on 06/08/2010

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NOTES:

1. MATERIAL: HOUSING - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0
COLOR: SEE TABLE ON SHEET 6 & 7
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0
COLOR: SEE TABLE ON SHEET 6 & 7
TERMINAL: COPPER ALLOY

2. FINISHES:
TERMINAL PLATING OPTIONS - SEE TABLE ON SHEET 6 & 7
3. PRODUCT SPECIFICATION: SEE TABLE ON SHEET 6 & 7
4. PACKAGING INFORMATION: PRODUCT SHALL BE PACKED IN TRAY
5. CARD SLOTS ACCEPTS 1.27±0.10MM MODULE THICKNESS
(MEASURED FROM PC PADS)

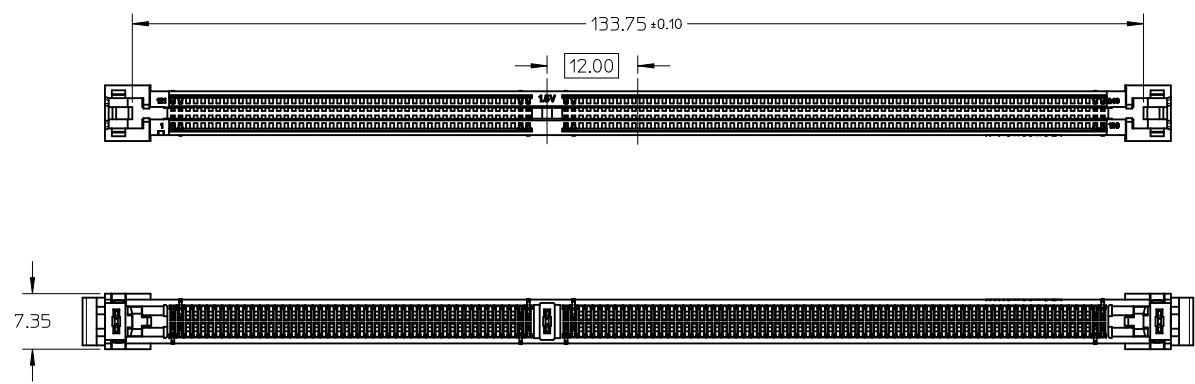
6. MOLEX LOGO, DATE CODE AND PART NO. INDICATED ON HOUSING
7. MODULE SEATING PLANE FROM TOP OF PCB
8. KEEP OUT ZONE RESERVED FOR LATCH

THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW CHKD: CTEH APPR: SHLENI 10	2010/04/23 2010/06/10 2010/06/13	DESCRIPTION REV	QUALITY SYMBOLS FA=0 FE=0 FP=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
						DRAWN BY DATE		TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL, T/H LOW LLCR MOLEX MOLEX INCORPORATED			
						CHECKED BY DATE					
						APPROVED BY DATE					
						MATERIAL NO.					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE TABLE		SD-78321-001				1 OF 7	
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

10 9 8 7 6 5 4 3 2 1

F



F

E

E

D

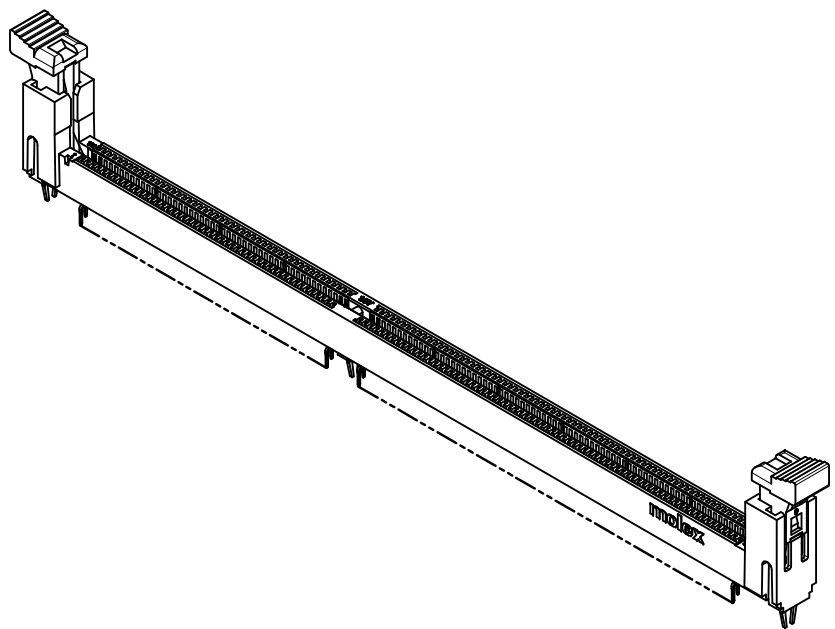
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C

C

B

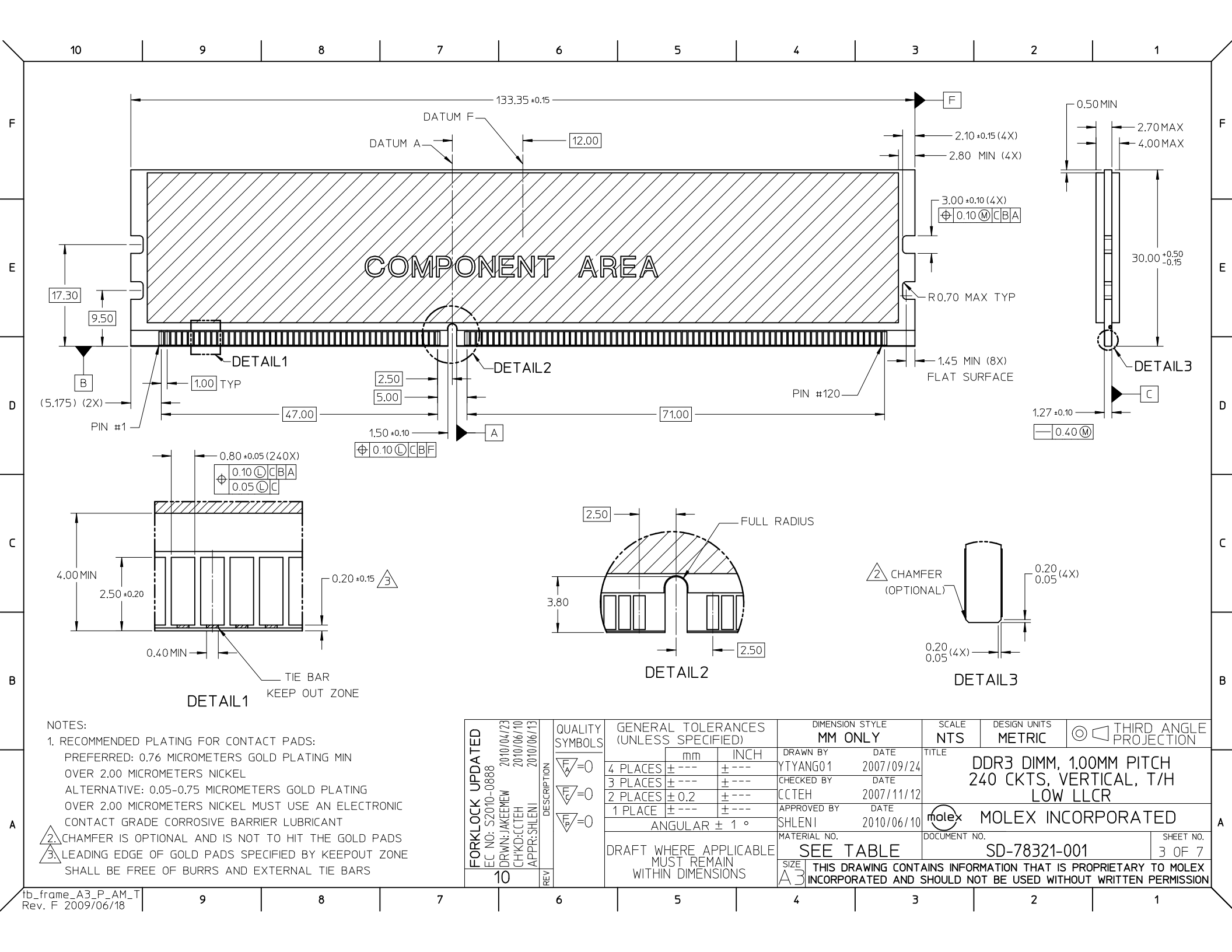
B



A

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/23 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13				DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
10		REV	$F_A=0$			mm	INCH	DRAWN BY YTYANG01	DATE 2007/09/24	TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL, T/H LOW LLCR				
			$F_C=0$		4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2007/11/12					
			$F_P=0$		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2010/06/10					
					2 PLACES	± 0.2	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78321-001		SHEET NO. 2 OF 7		
	1 PLACE	± ---	± ---											
				ANGULAR ± 1 °										
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS										
							SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

9 8 7 6 5 4 3 2 1



NOTES:

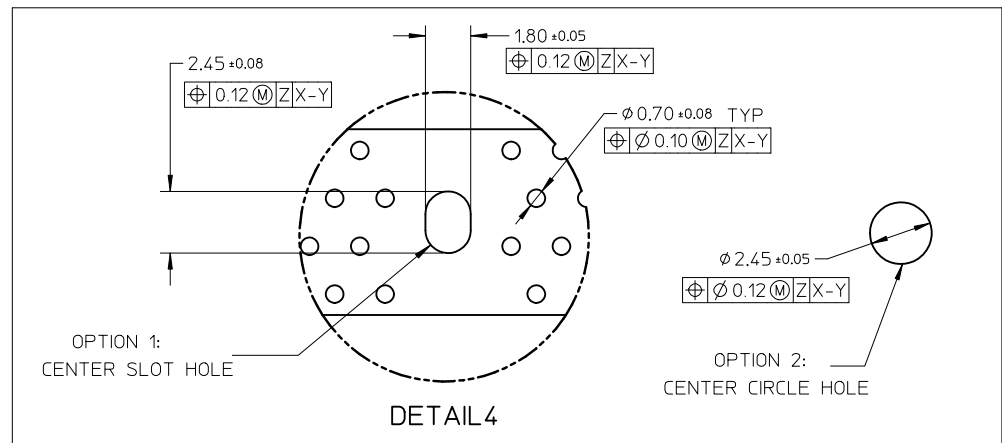
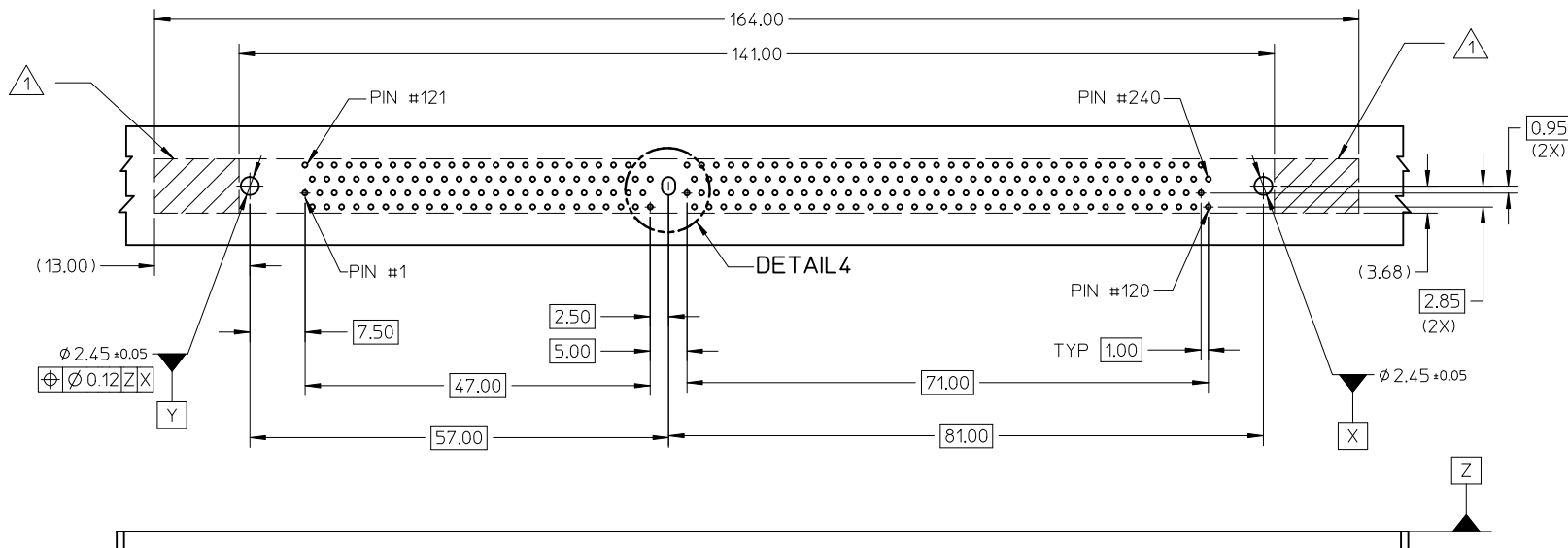
1. RECOMMENDED PLATING FOR CONTACT PADS:

PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
OVER 2.00 MICROMETERS NICKEL

ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC
CONTACT GRADE CORROSIVE BARRIER LUBRICANT

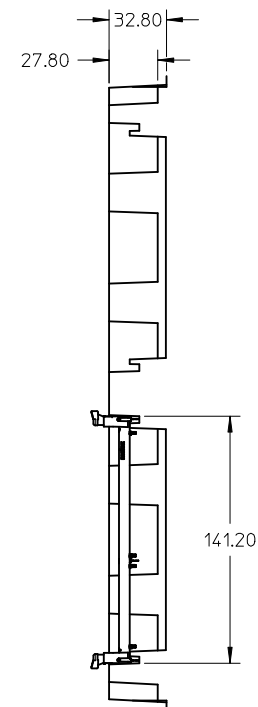
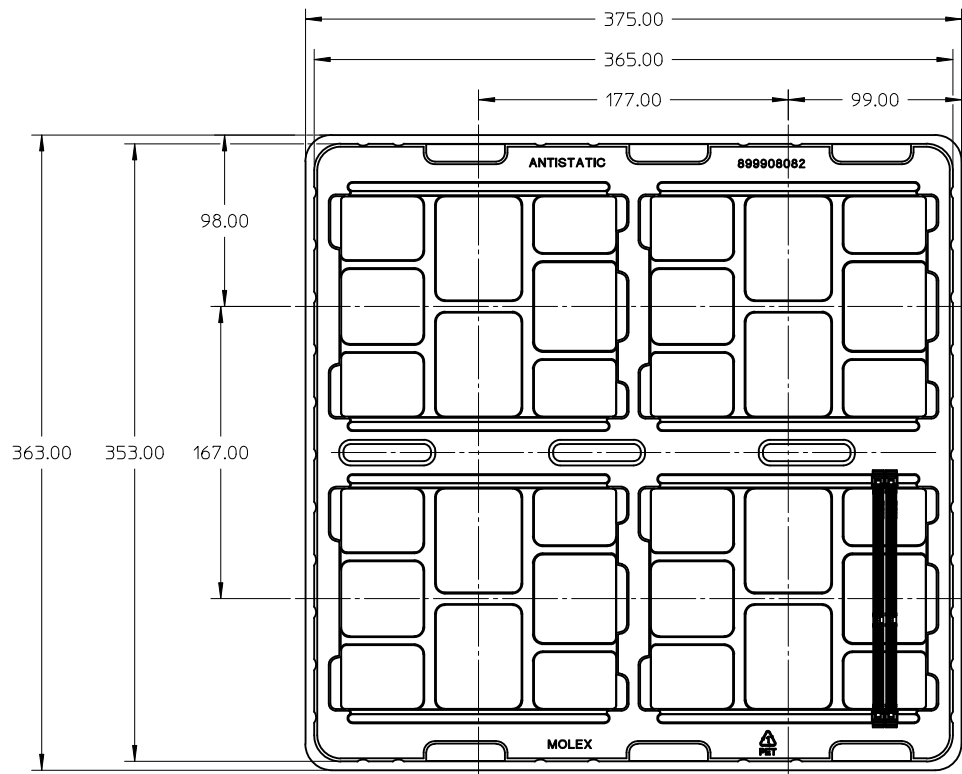
2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEP-OUT ZONE
SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

FORKLOCK UPDATED EC NO: S2010-0888 2010/04/23 DRWN: JAKEEWE 2010/06/10 CHKD: CTEH 2010/06/13 APPR: SHLENI	DESCRIPTION	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
				mm	INCH	DRAWN BY YTYANG01	DATE 2007/09/24	TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL, T/H LOW LLCR					
			4 PLACES	± ---	± ---	CHECKED BY CTEH	DATE 2007/11/12						
			3 PLACES	± ---	± ---	APPROVED BY SHLENI		DATE 2010/06/10	MOLEX INCORPORATED				
			2 PLACES	± 0.2	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78321-001					
1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



NOTE:
1. KEEPOUT AREA IS THE AREA WHERE THE CONNECTOR
(INCLUDING LATCH) IS MOUNTED ON PCB

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/23 CHKD: CTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY YTYANG01	DATE 2007/09/24	TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL, T/H LOW LLCR MOLEX INCORPORATED SD-78321-001	
						CHECKED BY CTEH	DATE 2007/11/12		
						APPROVED BY SHLENI	DATE 2010/06/10		
				ANGULAR $\pm 1^\circ$		MATERIAL NO.		DOCUMENT NO.	SHEET NO.
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE			
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



NOTES:
1. QTY OF CAVITY : 20 X 4 = 80 PCS

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				mm	INCH	DRAWN BY YTYANG01	DATE 2007/09/24	TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL, T/H LOW LLCR				
			4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2007/11/12					
			3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2010/06/10	molex MOLEX INCORPORATED				
			2 PLACES	± 0.2	± ---	MATERIAL NO.						
1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78321-001		5 OF 7			
10	REV				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

